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**AMENDMENTS TO THE SPECIFICATION:**

Please replace the second full paragraph on page 35 with the following paragraph:

For comparison, Fig. 18 shows frequency characteristics obtained in examples in which, in the above SAW filter device having the capacitance ratio  $C_{p2}/C_{p1} = 5$ , the bonding wire 113B is connected to the second parallel arm resonator 112b such that an inductance of about 1.0 nH is generated and such that an inductance of about 1.3 nH is generated. In Fig. 18, the solid line indicates the example of an inductance of about 1.0 nH, and the broken line indicates the example of an inductance of about 1.3 nH. As clearly seen in Fig. 18, as the inductance of the bonding wire ~~113b~~ 113B connected to the second parallel arm resonator 112b increases, attenuation in the vicinity of 2700 MHz deteriorates.

Please replace the second full paragraph on page 37 with the following paragraph:

The SAW filter device 200 includes series arm resonators 211a and 211b provided in a series arm extending between an input end 200A and an output end 200B. A first parallel arm resonator 212a is connected to the input end 200A, and an inductor 213a is connected to the first parallel arm resonator 212a. A second parallel arm resonator 212b is connected to a junction Y between the series arm resonators 211a and ~~211B~~ 211b. Inductors 213b1 and 213b2 are connected in series to the parallel arm resonator 212b, with one end of each inductor grounded. The inductors 213b1 and 213b2 are connected to each other in parallel.

Please replace the first full paragraph on page 39 with the following paragraph:

The parallel arm resonators 212a and 212b are electrically connected via bonding wires 213A, and 213B1 and 213B2 to the electrode pads 201a, 201c, and 201f. In this case, the length of the bonding wire 213A is selected such that an inductance of

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approximately about 1 nH is generated by the bonding wire 213A. The bonding wires 213B1 and 213B2 are connected to the electrode pads 201c and 201f, which are separate, wherein an inductor defined by bonding wires 213B1 and 213B2 having an inductance of about 0.55 nH is connected in series between the parallel arm resonator 212b and the ground potential.